

Title (en)

A METHOD FOR REMOVING SURFACE CONTAMINANTS ON MOULDS USED IN SEMICONDUCTOR PACKAGING TOOLS

Title (de)

VERFAHREN ZUM ENTFERNEN VON OBERFLÄCHENVERUNREINIGUNGEN VON IN HALBLEITERVERPACKUNGSWERKZEUGEN VERWENDETEN FORMEN

Title (fr)

PROCEDE PERMETTANT D'ELIMINER LES CONTAMINANTS DE SURFACE DE MOULES UTILISES SUR DES OUTILS D'ENCAPSULATION DE SEMICONDUCTEURS

Publication

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Application

EP 98936795 A 19980706

Priority

- SG 9800058 W 19980706
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Abstract (en)

[origin: WO9930845A1] The present invention utilizes laser to remove the surface contaminants such as grease, wax, and resin residue from a mould used in semiconductor packaging tools. The contaminant removal process utilizing the laser involves shooting a beam of laser onto the surface of the mould having the contaminants. The laser is delivered as a pulse which lasts only a short duration. Multiple pulses may be required to completely remove the contaminants. Because the area of coverage for each pulse is usually much smaller than the total area of the mould surface, the laser needs to be moved around until the entire mould surface has been exposed to the laser. Because fumes are produced as the laser disintegrates the contaminants, some type of vacuum should be used to remove the residual gas and other debris.

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CPC (source: EP)

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Citation (search report)

- [YA] EP 0233755 A2 19870826 - AMOCO CORP [US]
- [XY] PATENT ABSTRACTS OF JAPAN vol. 013, no. 365 (M - 859) 15 August 1989 (1989-08-15) & DATABASE WPI Section Ch Week 198925, Derwent World Patents Index; Class A32, AN 1989-183271 [25], XP002244738
- See references of WO 9930845A1

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